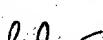


09/762823

		Subclass	Class	ISSUE CLASSIFICATION	FILED UNDER 35 U.S.C. 371			PATENT NUMBER 4201
BEST AVAILABLE COPY								
U.S. UTILITY Patent Application								
<div style="display: flex; align-items: center; justify-content: space-between;"> <div style="flex: 1; padding: 5px;">  SCANNED </div> <div style="flex: 1; padding: 5px;"> O.I.P.E.  Q.A.  </div> </div>				PATENT DATE				
APPLICATION NO. 09/762823	CONT/PRIOR D	CLASS 166-428	SUBCLASS 214	ART UNIT 1714	EXAMINER 			
APPLICANTS Itsuo Watanabe Kenzo Takefuwa Akira Nagai Kazuhiro Isaka								
TITLE Adhesive for bonding circuit members, circuit board, and method of Producing the same								
APPLICANT/ISR								

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
	(Assistant Examiner)		(Date)		
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____				ISSUE FEE	
	(Primary Examiner)		(Date)		
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	
	(Legal Instruments Examiner)		(Date)		

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